

Application No. 10/659,550

AMENDMENTS TO THE CLAIMS

A detailed listing of all claims that are, or were, in the present application, irrespective of whether the claim(s) remains under examination in the application are presented below. The claims are presented in ascending order and each includes one status identifier. Those claims not cancelled or withdrawn but amended by the current amendment utilize the following notations for amendment: 1. deleted matter is shown by strikethrough for six or more characters and double brackets for five or less characters; and 2. added matter is shown by underlining.

1. (Currently Amended) A combined member of aluminum-ceramics characterized by comprising a ceramic board, a circuit-receptive conductive member ~~holding electronic parts thereon~~, formed on one surface of the ceramic board, and a heat radiating member of aluminum or aluminum alloy heat-molded ~~bonded~~ directly on the other surface of the ceramic board.
2. (Original) The combined member as claimed in claim 1, wherein the heat radiating member is larger in dimension than the ceramic board.
3. (Currently Amended) The combined member as claimed in claim 1, wherein the heat radiating member has a[[n]] wall enclosing the ceramic board.
4. (Original) The combined member as claimed in claim 1, wherein the heat radiating member has a terminal base.
5. (Original) The combined member as claimed in claim 3, wherein the heat radiating member has a terminal base.

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6. (Original) The combined member as claimed in claim 1, wherein the heat radiating member contains copper.
7. (Original) The combined member as claimed in claim 3, wherein the heat radiating member contains copper.
8. (Original) The combined member as claimed in claim 4, wherein the heat radiating member contains copper.
9. (Currently Amended) A combined member of aluminum-ceramics characterized by comprising an electrically insulating ceramic board, a circuit-receptive conductive member ~~holding electronic parts thereon~~, formed on one surface of the ceramic board, and a water cooling jacket of aluminum or aluminum alloy bonded directly on the other surface of the ceramic board.
10. (Original) The combined member as claimed in claim 9, wherein the water cooling jacket contains copper.
11. (Original) The combined member as claimed in claim 1, wherein the direct bonding is carried out by a molten bonding method.
12. (Original) The combined member as claimed in claim 9, wherein the direct bonding is carried out by a molten bonding method.

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13. (Original) The combined member as claimed in claim 1, wherein the main component of the ceramic board is one of alumina, aluminum nitride and silicon nitride.

14. (Original) The combined member as claimed in claim 9, wherein the main component of the ceramic board is one of alumina, aluminum nitride and silicon nitride.

15. (Currently Amended) A combined member of aluminum-ceramics characterized by comprising a plurality of ceramic boards, a circuit-receptive conductive member ~~holding electronic parts thereon~~, formed on one surface of each of the ceramic boards, and a heat radiating member of aluminum or aluminum alloy heat-molded ~~bonded~~ directly on the other surface of each of the ceramic boards.

16. (Currently Amended) A combined member of aluminum-ceramics characterized by comprising a plurality of electrically insulating ceramic boards, a circuit-receptive conductive member ~~holding electronic parts thereon~~, formed on one surface of each of the ceramic boards, and a water cooling jacket of aluminum or aluminum alloy bonded directly on the other surface of each of the ceramic boards.

17-20. (Canceled)